



YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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Features

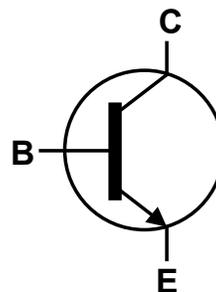
- $BV_{CEO} > 45V$
- $I_C = 2A$ high Continuous Collector Current
- I_{CM} up to 6A Peak Pulse Current
- High gain $h_{FE} > 400 @ 1A$
- 2W Power Dissipation
- Low saturation voltage $V_{CE(sat)} < 300mV @ 1A$
- Complementary PNP type: NK-FCX790A

Mechanical Data

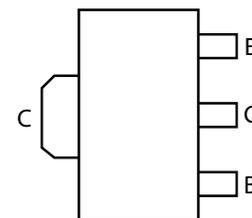
- Case: SOT89
- Case material: molded plastic. "Green" molding compound.
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 e3
- Weight: 0.052 grams (Approximate)



Top View



Device Symbol



Top View
Pin Out

Maximum Ratings (@ $T_A = +25^{\circ}\text{C}$, unless otherwise specified.)

| Characteristic | Symbol | Limit | Unit |
|------------------------------|-----------|-------|------|
| Collector-Base Voltage | V_{CBO} | 45 | V |
| Collector-Emitter Voltage | V_{CEO} | 45 | V |
| Emitter-Base Voltage | V_{EBO} | 7 | V |
| Continuous Collector Current | I_C | 2 | A |
| Peak Pulse Current | I_{CM} | 6 | A |
| Base Current | I_B | 500 | mA |

Thermal Characteristics (@ $T_A = +25^{\circ}\text{C}$, unless otherwise specified.)

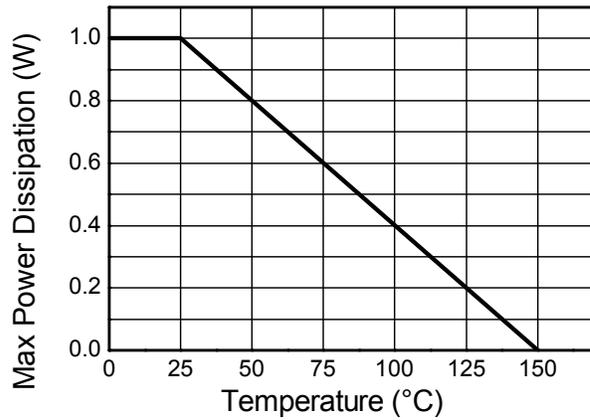
| Characteristic | Symbol | Value | Unit |
|---|-----------------|------------------|----------------------|
| Power Dissipation | P_D | (Note 5) 1 | W |
| | | (Note 6) 2 | |
| Thermal Resistance, Junction to Ambient Air | $R_{\theta JA}$ | (Note 5) 125 | $^{\circ}\text{C/W}$ |
| | | (Note 6) 62.5 | |
| Thermal Resistance, Junction to Leads | $R_{\theta JL}$ | 5.31 | $^{\circ}\text{C/W}$ |
| Operating and Storage Temperature Range | T_J, T_{STG} | -55 to +150 | $^{\circ}\text{C}$ |

ESD Ratings (Note 8)

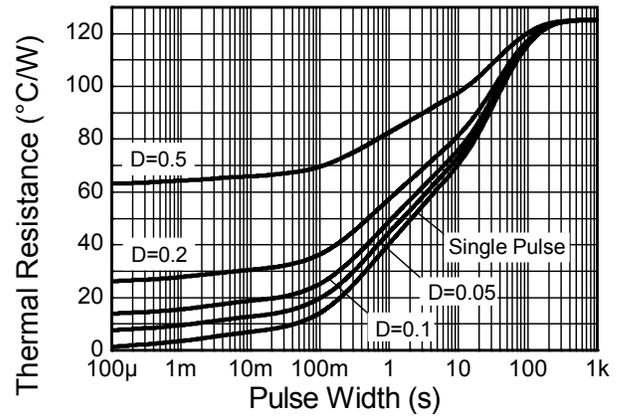
| Characteristic | Symbol | Value | Unit | JEDEC Class |
|--|---------|--------------|------|-------------|
| Electrostatic Discharge - Human Body Model | ESD HBM | $\geq 8,000$ | V | 3B |
| Electrostatic Discharge - Machine Model | ESD MM | ≥ 400 | V | C |

- Notes:
5. For a device surface mounted on 15mm x 15mm x 0.6mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions; the device is measured when operating in steady state condition.
 6. Same as note (5), except the device is mounted on 40mm x 40mm x 1.6mm FR4 PCB.
 7. Thermal resistance from junction to solder-point (on the exposed collector pad).
 8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

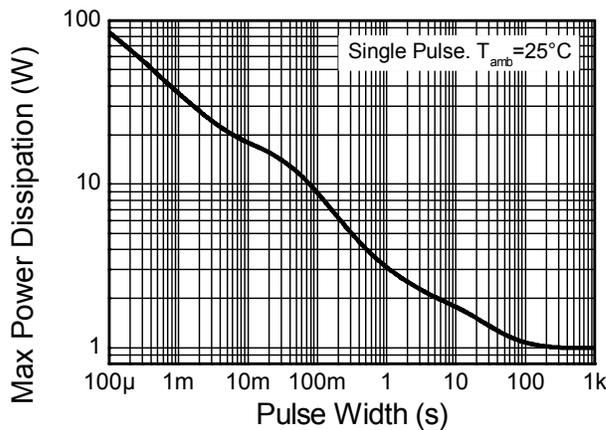
Thermal Characteristics and Derating Information



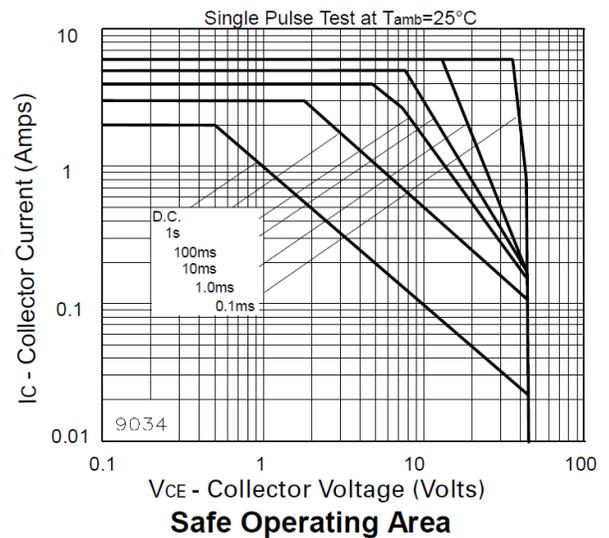
Derating Curve



Transient Thermal Impedance



Pulse Power Dissipation



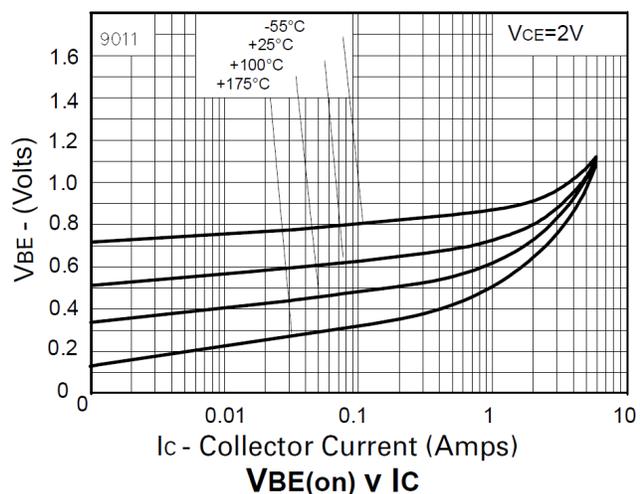
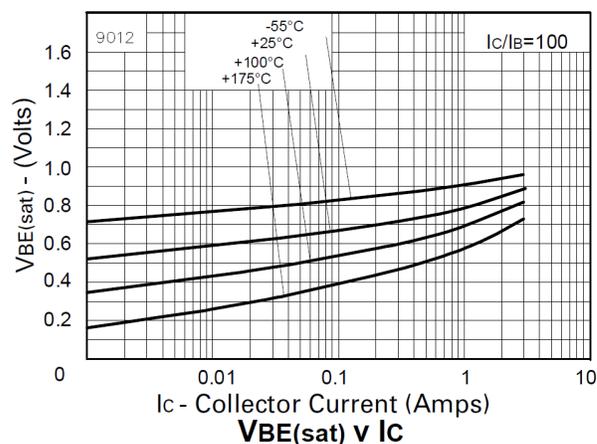
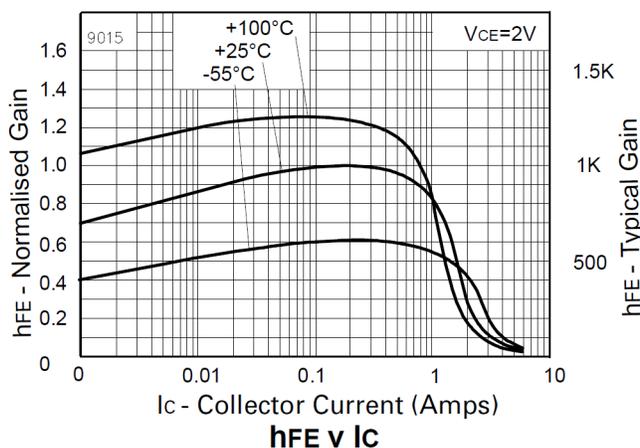
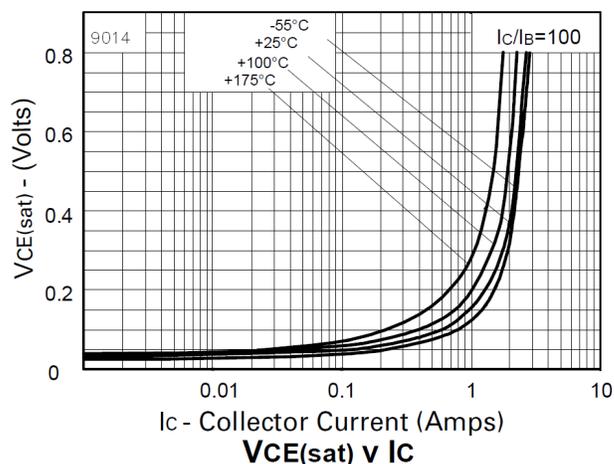
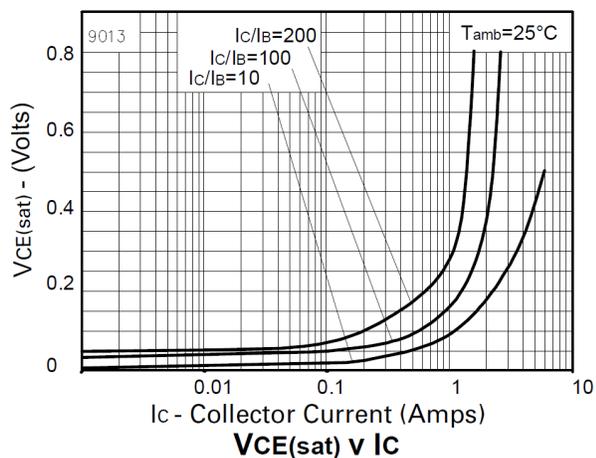
Safe Operating Area

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

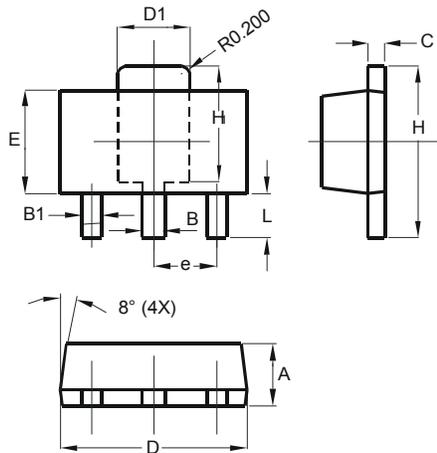
| Characteristic | Symbol | Min | Typ. | Max | Unit | Test Condition |
|---|----------------------|-----|------|------|------|--|
| Collector-Base Breakdown Voltage | BV _{CB0} | 45 | — | — | V | I _C = 100μA |
| Collector-Emitter Breakdown Voltage (Note 9) | BV _{CEO} | 45 | — | — | V | I _C = 10mA |
| Emitter-Base Breakdown Voltage | BV _{EB0} | 7 | — | — | V | I _E = 100μA |
| Collector Cutoff Current | I _{CB0} | — | — | 100 | nA | V _{CB} = 35V |
| Emitter Cutoff Current | I _{EB0} | — | — | 100 | nA | V _{EB} = 5.6V |
| DC current transfer Static ratio (Note 9) | h _{FE} | 500 | — | — | — | I _C = 100mA, V _{CE} = 2V |
| | | 400 | — | — | | I _C = 1A, V _{CE} = 2V |
| | | 150 | — | — | | I _C = 2A, V _{CE} = 2V |
| Collector-Emitter Saturation Voltage (Note 9) | V _{CE(sat)} | — | — | 80 | mV | I _C = 0.1A, I _B = 0.5mA |
| | | — | — | 300 | | I _C = 1A, I _B = 5mA |
| Base-Emitter Saturation Voltage (Note 9) | V _{BE(sat)} | — | — | 0.9 | V | I _C = 1A, I _B = 10mA |
| Base-Emitter Turn-on Voltage (Note 9) | V _{BE(on)} | — | — | 0.85 | V | I _C = 1A, V _{CE} = 2V |
| Transitional Frequency | f _T | 150 | — | — | MHz | I _C = 50mA, V _{CE} = 5V f = 50MHz |
| Input capacitance | C _{ibo} | — | 200 | — | pF | V _{EB} = 0.5V, f = 1MHz, |
| Output capacitance | C _{obo} | — | 16 | — | pF | V _{CB} = 10V, f = 1MHz, |
| Switching times | t _{on} | — | 33 | — | ns | I _C = 500mA, V _{CC} = 10V I _{B1} = -I _{B2} = 50mA |
| | t _{off} | | 1300 | | | |

Note: 9. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

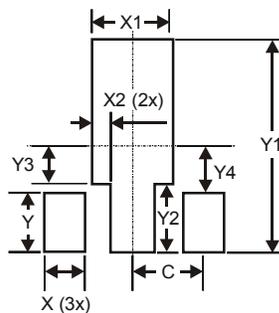


Package Outline Dimensions



| SOT89 | | |
|----------------------|----------|------|
| Dim | Min | Max |
| A | 1.40 | 1.60 |
| B | 0.44 | 0.62 |
| B1 | 0.35 | 0.54 |
| C | 0.35 | 0.44 |
| D | 4.40 | 4.60 |
| D1 | 1.62 | 1.83 |
| E | 2.29 | 2.60 |
| e | 1.50 Typ | |
| H | 3.94 | 4.25 |
| H1 | 2.63 | 2.93 |
| L | 0.89 | 1.20 |
| All Dimensions in mm | | |

Suggested Pad Layout



| Dimensions | Value (in mm) |
|------------|---------------|
| X | 0.900 |
| X1 | 1.733 |
| X2 | 0.416 |
| Y | 1.300 |
| Y1 | 4.600 |
| Y2 | 1.475 |
| Y3 | 0.950 |
| Y4 | 1.125 |
| C | 1.500 |